



L Number	Hits	Search Text	DB	Time stamp
5	55526	metal with wire	USPAT;	2001/11/03 17:57
			US-PGPUB	
6	25439	(metal with wire) and (insulat\$3	USPAT;	2001/11/03 17:57
		dielectric)	US-PGPUB	
7	2062	((metal with wire) and (insulat\$3	USPAT;	2001/11/03 17:58
		dielectric)) and (glass with substrate)	US-PGPUB	
8	926		USPAT;	2001/11/03 17:23
		dielectric)) and (glass with substrate))	US-PGPUB	
		and (semiconductor with (chip substrate))		
9	901	((((metal with wire) and (insulat\$3	USPAT;	2001/11/03 17:58
		dielectric)) and (glass with substrate))	US-PGPUB	
		and (semiconductor with (chip substrate)))		
		and (contact via hole open\$4)		
10	58366	metal with wire	EPO; JPO;	2001/11/03 17:57
· ·			DERWENT;	
			IBM TDB	/ /
11	12121	(metal with wire) and (insulat\$3	EPO; JPO;	2001/11/03 17:58
		dielectric)	DERWENT;	
			IBM TDB	
12	142		EPO; JPO;	2001/11/03 17:58
		dielectric)) and (glass with substrate)	DERWENT;	
			IBM TDB	
13	54	1 , , ,	EPO; JPO;	2001/11/03 17:59
		dielectric)) and (glass with substrate))	DERWENT;	
		and (contact via hole open\$4)	IBM TDB	

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